

**RoHS
Compliant**



Description

Surface cure thermal interface paste specially designed to resist pumping out from the bond line. It can be applied using industrial dispensing equipment or via screen/stencil printing techniques.

Applications

- Automotive ECU (electronic control units)
- Power Supplies
- Microprocessors
- Displays and consumer electronics

Features

- Long term thermal stability
- Recommended for applications with rapid temperature cycling
- Easily dispensable
- Fast curing time (when heated)

Properties

Characteristic	Value
Colour	Part A - Yellow Part B - White
Thermal Conductivity (ASTM D5470)	1.8W/mK
Volume Resistivity Ohm-m	10 ¹²
Specific Gravity	2.7g/cm ³
Dielectric Breakdown	>10kV/mm
Dielectric Constant	7
Heat Capacity	1J/mK
Flammability	V-0
Application Temperature	-60°C to +200°C
Hardness	40
Tensile Strength	0.2MPa
Elongation	100%

Part Number Table

Description	Part Number
2-Part Dispensible Thermal Gap Filler, Yello/White, 2W/mK, 200ml	MPGCS-DGP20-2P

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